PATENT ASSIGNMENT

Electronic Version v07 Stylesheet Version v02

SUBMISSION TYPE:		NEW ASSIGNMENT APPLICATION NUMBER 10/604600					
NATURE OF CONVEYANCE:			ASSIGNMENT OF ASSIGNOR'S INTEREST				
CONVEYING PARTY DATA							
Name	9		Execution Date				
Kuo-Chien Wu		2003	3-08-04				
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RECEIVING PARTY DATA							
Name	Street Address	5	Internal Address	City	State/Country	Postal Code	
NANYA TECHNOLOGY CORP.	HWA-YA TECHNOLOGY PARK 669, FUHSING 3 RD.,		KUEISHAN	Tao-Yuan Hsien	TAIWAN		
CORRESPONDENCE DATA FAX NUMBER: 886229295950 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO. CUSTOMER NUMBER: 027765							
NAME OF PERSON SIGNING:		WINSTON HSU					
DATE SIGNED:		2003-08-04					
Total Attachments: 2 source=NTCP0006ASS1.tif source=NTCP0006ASS2.tif							

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNORS (Inventors):

Name:	Kuo-Chien Wu	Nationality: R.O.C.				
Address:	No. 547, Chung-Cheng Rd., Chung-Miao Li, Miao- Li Hsien, Taiwan, R.O.C.					
Name	Yinan Chen	Nationality: R.O.C.				
Address:	No. 4, Lane 151, Chien-Min Rd., Pei-Tou, Taipei City, Taiwan, R.O.C.					
(hereinafter 'As	ssignee'), of (Assignee					
HWA-YA TE	CHNOLOGY PARK	669, FUHSING 3 RD., KUEISHAN, Tao-Yuan Hsien,				
Taiwan, R.O.O	<u></u>					
1.1	· · · · · · · · · · · · · · · · · · ·	an anticipation of the ASSIGNIEE the entire right title and				

, and the successors assigns and legal representatives of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"METHOD OF FABRICATING CONTACT HULES ON A SEMICONDUCTOR CHIP"

Which is found in :

(a)		U.S.	patent	application	executed	on ever	date
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(b) U.S. patent application executed on _____

(c) U.S. application serial no.

(d) _____ patent no. _____ issued _____

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PATENT REEL: 013844 FRAME: 0172

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and, in and to, all Letters Patent to be obtained for said invention by the above application or ant continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or reexamination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF. We have hereunto set hand and seal this ______ (Date of signing).

(Type name of inventor)	Signature of INVENTOR				
Kuo-Chien Wu	Kuc-Chien Wh				
<u>Yinan Chen</u>	Jiman Chen				

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RECORDED: 08/04/2003